

Seventh International Indentation Workshop (IIW7)

Incorporating **small scale/in-situ testing**

University of Hyderabad, India

17 to 21 December 2023

www.iiw7uohyd.in

Email: iiw7@uohyd.ac.in

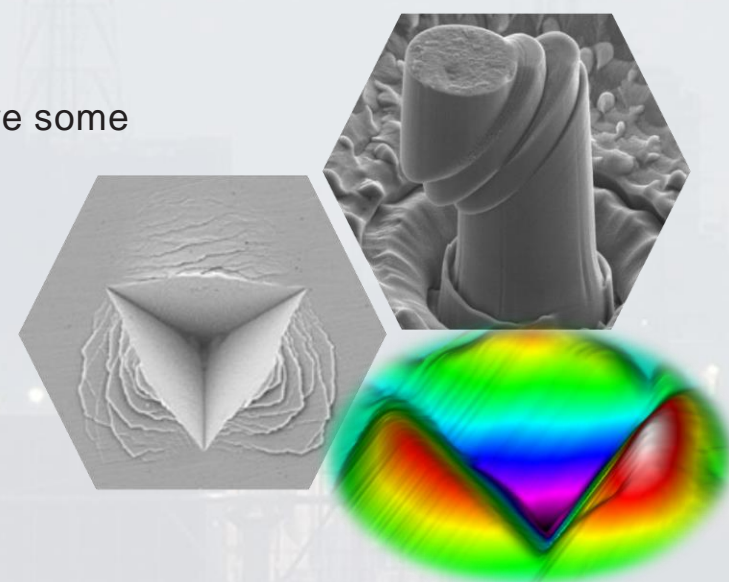
Scope

The Seventh International Indentation Workshop (IIW7) will provide an opportunity to exchange the recent understanding of the indentation method, its utilization for understanding the mechanical and functional properties of a wide variety of materials, and advances in instrumentation. Since nanoindentation is a technique that pioneered the probing of small volumes, allied experimental techniques such as micropillar compression and in-situ techniques such as tensile testing in TEM, will also be included. Recent advances in the theoretical and computational aspects of all the above also will be discussed. The technical program will include plenary, invited, and contributed oral and poster presentations.

Topics

All the research topics related to indentation will be covered. Following are some themes (not an exhaustive list).

- Analysis of deformation and fracture during indentation
- Modeling and simulation of mechanical behavior on a small scale
- Extracting mechanical properties and multi-scale modeling
- Advanced nanomechanical characterization, including in-situ probing
- New developments and improvements in mechanical testing
- Instrumented indentation under different environmental conditions
- Application to the broad area of inorganic and organic materials



Plenary/Invited Speakers

- **Jorge Alcalá**, Universitat Politècnica de Catalunya, Spain
- **Srinivasan Chandrasekar**, Purdue University, USA
- **Yang-Tse Cheng**, University of Kentucky, USA
- **Ming Dao**, Massachusetts Institute of Technology, USA
- **Pijush Ghosh**, IIT Madras
- **Finn Giuliani**, Imperial College, UK
- **Mathias Göken**, Friedrich Alexander University, Germany
- **Jae-il Jang**, Hanyang University, South Korea
- **Vikram Jayaram**, Indian Institute of Science, Bangalore
- **Surya Kalidindi**, Georgia Institute of Technology, USA
- **Ikeda Ken-ichi**, Hokkaido University, Japan
- **Dongil Kwon**, Seoul National University, South Korea
- **Frantisek Lofaj**, Institute of Materials Research of SAS, Slovakia
- **Robert Maaß**, Federal Inst. of Materials Research and Testing, Germany
- **Wakeda Masato**, National Institute for Materials Science, Japan
- **Amit Misra**, University of Michigan, USA
- **Sundeep Mukherjee**, University of North Texas, USA
- **Alfonso Ngan**, The University of Hong Kong, Hong Kong
- **Tanguy Rouxel**, Université de Rennes, France
- **Gi-Dong Sim**, Korea Adv. Institute of Science & Technology, South Korea
- **Ghatu Subhash**, University of Florida, USA
- **Changquan Calvin Sun**, University of Minnesota, USA
- **Venkatesh T**, Stony Brook University, USA
- **Ohmura Takahito**, National Institute for Materials Science, Japan
- **Alexey Useinov**, Technical Institute of Superhard and Novel Carbon Materials, Russia
- **Yakai Zhao**, Nanyang Technological University, Singapore

Organizing Committee

- **Upadrasta Ramamurty**, NTU, Singapore (Chair)
- **Jaiprakash Gautam**, UoH, Hyderabad (Convener)
- **Kiran Mangalampalli**, SRM IST, Chennai (Co-convener)
- **P. Sudharshan Phani**, ARCI, Hyderabad (Co-convener)
- **Vikram Jayaram**, Indian Institute of Science, Bangalore
- **Syed Asif**, InduStron, Thiruvananthapuram
- **C. Malla Reddy**, IISER Kolkata, Kolkata
- **Koteswararao V Rajulapati**, UoH, Hyderabad
- **K. Eswar Prasad**, IIT Indore, Indore
- **R. L. Narayan**, IIT Delhi, New Delhi
- **Nagamani Jaya Balila**, IIT Bombay, Mumbai
- **K. Rajesh**, IIT Hyderabad, Hyderabad

Registration: [15th July – 10th August, 2023]

Overseas Participants: Regular (400 US\$), Students (200 US\$)

Indian Participants: Regular (₹10000/-), Students (₹5000/-)

(Excluding Accommodation and Applicable Taxes)

Abstract Submission:

Start Date: 15th May, 2023

Last Date: 1st July, 2023

Acceptance Notification: From 15th July 2023

